# RSC Advances



This is an *Accepted Manuscript*, which has been through the Royal Society of Chemistry peer review process and has been accepted for publication.

*Accepted Manuscripts* are published online shortly after acceptance, before technical editing, formatting and proof reading. Using this free service, authors can make their results available to the community, in citable form, before we publish the edited article. This *Accepted Manuscript* will be replaced by the edited, formatted and paginated article as soon as this is available.

You can find more information about *Accepted Manuscripts* in the Information for Authors.

Please note that technical editing may introduce minor changes to the text and/or graphics, which may alter content. The journal's standard Terms & Conditions and the Ethical quidelines still apply. In no event shall the Royal Society of Chemistry be held responsible for any errors or omissions in this *Accepted Manuscript* or any consequences arising from the use of any information it contains.



www.rsc.org/advances

# **Journal Name**

# ARTICLE

Received 00th Janu ary 20xx, Accepted 00th January 20xx

DOI: 10.1039/x0xx00000x

**www.rsc.org/**



A. Dennyson Savariraj,<sup>a</sup> G. Rajendrakumar,<sup>a</sup> Samayanan Selvam,<sup>a</sup> S.N.Karthick B.Balamuralitharan,<sup>a</sup> Hee-Je Kim,<sup>a</sup> Kodakkal Kannan Viswanathan,<sup>b</sup> M. Vijaykumar Kandasamy Prabakar a\*

It is found that electrocatalytic activity of Cu<sub>2</sub>-x<sub>S</sub> thin films used in quantum dots sensitized solar cells (QDSSC) as countner electrode (CE) for the reduction of polysulfide electrolyte depends on the surface active sulfide and disulfide species  $\epsilon$ deficiency of Cu. The preferential bonding between  $Cu^{2+}$  and  $S^2$  leading to the selective formation of Cu<sub>1.8</sub>S stacked platelets like morphology is determined by Cetyl Trimethyl Ammonium Bromide surfactant with temperature and crab li Cu-S coordination bond formed dictates the surface area to volume ratio of the Cu<sub>1.8</sub>S thin films and the electrocatalytic activity. The Cu deficiency enhances the conductivity of the  $Cu<sub>1.8</sub>S$  thin films and exhibits near- infrared localized surface plasmon resonance due to free carriers and UV-VIS absorption spectra shows excitonic effect due to quantum size effect When these Cu<sub>1.8</sub>S thin films were employed as CE in QDSSC, robust photoconversion efficiency of 5.2 % is yielded for t. film deposited at 60 ˚C by a sinlge step chemical bath deposition method.

## **1.Introduction**

Quantum dot sensitized solar cells (QDSSC) emerged as an alternative to dye sensitized solar cells (DSSC) which failed due to photo degradation in spite of being cost effective. $^1$  To overcome this, inorganic quantum dots (QDs) are used as photosensitizer due to generation of multiple excitons through impact ionization with single photon absorption in addition to band gap tunability.<sup>2-4</sup> QDs incorporated in to the photoanode absorb incident light over a wide range of spectral wavelength with flexible tandem arrangement.<sup>1,5</sup> Even though, QDSSCs outperform organo metallic dye based DSSCs in terms of stability against photo degradation, the photovoltaic performance is still very low.<sup>6-9</sup> Many efforts have been made to improve the efficiency by employing cascade layers of FTO/TiO<sub>2</sub> with different QDs such as PbS,  $^{10}$  CdS,  $^{11}$  CdSe,  $^{12}$  and CdS/CdSe hetero structures  $^{13}$  as efficient sensitizers in QDSSCs with enhanced charge separation due to large intrinsic dipole moment.<sup>13</sup> In QDSSC, counter electrode (CE) is an equally

*a. Department of Electrica l and Compute r Engineering, Pusan National University, San 30, Ja ngjeong-Dong, Gumjeong-Ku, Busan-609 735, South K orea.*

*b. UTM Centre for Industrial a nd Applied Ma thematics, Department of* 

*Mathematical Sciences, Un iversiti Teknologi Mala ysia, 81310 , Joho r Bah ru, Joho r, Malaysia .*

*c. Pacific No rthwest Na tional Laborato ry (P NNL) , Rich land, WA -99354, USA*

<sup>†</sup> Footn otes relating to the title and/or au thors sho uld appear here.

Electronic Supplementary Information (ESI) available: [details of any supplementary information available should be included here]. See DOI: 10.1039/x0x x00000x

process with controlled nucleation is very handy. Therefore, several experimental parameters such as concentration, temperature, reaction time and concentration of surfactants or capping agents or structure- directing agent (SDA) are to be fine-tuned to obtain both size and shape controlled  $Cu_{2-x}S$ nanostructures <sup>24</sup>. Cetyl Trimethyl Ammonium Bromide (CTAB) is one such SDA that binds well with the  $Cu_{2-x}S$  coordination formed in the initial stage and as the reaction proceeds it determines the shape and morphology of the  $Cu_{2-x}S$  thin films to be synthesized.

Moreover, it is essential to optimize the molarity, quantity of precursor solutions, temperature and position of substrate inside the growth vial in order to assure quality of the films grown by chemical bath deposition (CBD) methods. Growth of  $Cu_{2-x}S$  thin film was not initiated below 55  $°C$  and the deposited films peeled off from the substrate above 65 ˚C. The  $Cu_{2-x}S$  thin films grown at optimized temperature were characterized like phase, composition, surface morphology and electrochemical properties associated with QDSSC. We strongly believe that our method is very simple and the clearly demonstrated growth method would allow the researchers to further tailor the properties of  $Cu_{2-x}S$  thin films to suit their needs. In this report, we have presented one step CTAB assisted synthetic route to fabricate stacked nano platelets like  $Cu_{2-x}S$  thin films using simple chemical bath deposition (CBD) by varying the deposition temperature for a period of 2 hours. It is found that both temperature and SDA influence the shape and surface morphology. The  $Cu_{2-x}S$  thin films synthesized possess stacked nano platelets like structure with large surface to volume ratio terminated with different surface active sulfide, disulfides and oxides. This in turn influences their electrocatalytic activity and particularly enhances the redox reaction of sulfide/polysulfide  $(S^2/S_n^2)$  redox couple electrolyte when the  $Cu_{2-x}S$  thin films are employed as CE for QDSSCs. The QDSSC fabricated using  $Cu_{2-x}S$  thin film synthesized at 60 °C giving a photo conversion efficiency of up to 5.2 % with consistent stability. Based on X-ray photoelectron spectroscopy (XPS), impedance spectroscopy and Tafel polarization, a detailed exploratory investigation of the electrocatalytic behavior of the CE is discussed and presented here.

#### **2. Experimental**

#### **2.1 Materials**

 $Cu<sub>2-x</sub>S$  of stacked nano platelets were successfully deposited by CBD using water as solvent on well cleaned fluorine doped tin oxide (FTO) of resistance 7  $Ω/cm²$  (Hartford Glass). All the precursors used for the synthesis were analytical grade and purchased from Sigma Aldrich and the synthesis was carried out without further purification.

#### **2.2 Preparation of photo anode and counter electrode**

**ARTICLE Journal Name**

The typical synthesis was carried out by dissolving 0.1 M of copper chloride (CuCl<sub>2</sub>.2H<sub>2</sub>O) in 50 ml of deionized water and 1.0 M of thioacetamide  $(CH_3CSNH_2)$  was added for S source followed by adding 1.1 M of acetic acid ( $CH<sub>3</sub>COOH$ ) in drops and stirred continuously. To the above solution,  $0.013$  M of CTAB ( $(C_{16}H_{33})$  N (CH<sub>3</sub>)<sub>3</sub>Br) was added and stirred vigorously for 25 minutes to make a homogeneous solution. The previously cleaned FTO glass substrates were immersed and kept horizontally in to the growth solution and chemical bath deposition was carried out for 2 hours at 55 °C, 60 °C and 65 °C and the samples were labelled CE55, CE60 and CE65 respectively. Above 65 °C, the deposited  $Cu_{2-x}S$  films were peeled off from the substrate and hence not suitable for CE. The CBD synthesized stacked  $Cu_{2-x}S$  nanoplatelts were then rinsed with deionized water and 99% ethanol and purged with  $N_2$  gas.

The photoanodes were prepared by coating commercial. available TiO<sub>2</sub> paste of particle size 20 nm (Ti-Nanoxide HT)<sup>6</sup> Solaronix) on the FTO using doctor blade method and were sintered at 450 °C for 30 minutes to evaporate the solvent The QDs photosensitizers were coated on the TiO<sub>2</sub> using successive ionic layer adsorption and reaction method (SILAR) with optimized conditions already reported elsewhere<sup>26</sup>. For CdS quantum dots, 0.025 M cadmium acetate dihydrate  $(C<sup>d</sup>)$  $(CH<sub>3</sub>COO)$ <sub>2</sub>. 2H<sub>2</sub>O and 0.2M sodium sulfide (Na<sub>2</sub>S) were prepared in 50 ml of deionized water separately for cation and anion sources respectivel y and 5 cycles of SILAR were carried out. For CdSe QDs, the cation sources was prepared by dissolving 0.025 M of (Cd (CH<sub>3</sub>COO)<sub>2</sub>. 2H<sub>2</sub>O) in 50 ml of deionized water. The anion source containing Se was prepared by from aqueous 0.2 M selenium (Se) and 0.4 M (Na<sub>2</sub>SO<sub>3</sub>) taken in a round bottom flask. This solution was refluxed at 125 °C for a period of two hours to get sodium selenosulfa'  $(Na<sub>2</sub>SeSO<sub>3</sub>)$  as selenium is not soluble in water and cannot react in pristine form. Using the above prepared cation and the anion precursors, 8 SILAR cycles of CdSe QDs was deposited, while the temperature of the precursors are kept 55 ˚C for better adsorption. Finally, to avoid corrosion due to the polysulfide electrolyte and back electron transfer into electrolyte, two SILAR cycles of zinc sulfide (ZnS) passivation layer was coated using 0.2 M of zinc nitrate hexahydrate  $(ZnNO<sub>3</sub>$ . 6H<sub>2</sub>O) and 0.2 M of Na<sub>2</sub>S solutions. RSCREED ADVANCES **ADVANCES ADVANCES ACCEPTED ACCEPT** 

#### **2.3 Fabrication of QDSSCs and Symmetric cells**

The QDSSCs were assembled by sandwiching the SILAR processed tandem layered TiO<sub>2</sub>/CdS/CdSe/ZnS photoanodes and chemical bath deposited  $Cu_{2-x}S$  and Pt CEs with a 25 $\mu$ m hot-melt sealing sheet (SX 1170-25, Solaronix) in betwee. them. The set up was heated at 110 °C in a hotplate for 45 seconds. Then, the internal space of the cell was filled with the sulfide/polysulfide  $(S^2 / S_n^{2})$  redox couple electroly comprising of 1M of Na<sub>2</sub>S, 2M of S and 0.2M of KCl by capillary action. In the case of symmetric cells, the photoanode  $w$  s replaced with CE itself such as  $Cu_{2-x}S/s$ ulfide-polysulfide (S<sup>2</sup>)  $\sqrt{S_n}^2$ )/ Cu<sub>2-x</sub>S and Pt in place of Cu<sub>2-x</sub>S served as reference we

#### **Journal Name ARTICLE**

sandwiched by a 25 µm hot-melt sealing sheet and the space between them were filled with polysulfide electrolyte.

#### **2.4. Characterizations**

The phase purity and crystallinity of  $Cu_{2-x}S$  thin films were analyzed using X-ray diffraction (XRD; Bruker D8-Advance) with Cu Ka radiation ( $\lambda$  =1.54056) source operated at 40 kV and 30 mA in the range of  $10 - 80^\circ$ . The surface morphology of the thin films was analyzed using (FE-SEM Hitachi, Model SU-70). UV-Vis spectroscopic analysis was carried out using optizen 3220 UV. X-ray photon spectroscopy (XPS) was performed using a VG scientific ESCALAB250 with monochromatic Al-Kα radiation of 1486.6 eV with an electron take off angle of 90˚. The survey spectrum was scanned in the binding energy (BE) range of 0.0 - 1400 eV in steps of 1 eV. The binding energy values reported here is relative to the carbon C 1s core level at 284.6 eV. The pressure of the chamber was maintained at  $10^{-10}$  torr throughout the measurement. The current-voltage characteristic of the QDSSCs were studied under 1 sun illumination (AM 1.5G 100m Wcm<sup>-2</sup>) with san Ei Electric (XES 301S, Japan) solar simulator having the irradiance uniformity of ±3%. Electrochemical impedance spectroscopy (EIS) was performed using a BioLogic potentiostat/galvanostat/EIS analyzer (SP-150, France) under 1 sun illumination.

#### **3. Result and Discussion**

**3.1 XRD- Analysis**



Figure 1 represents the X-ray diffraction pattern of CBD deposited  $Cu<sub>2-x</sub>S$  thin films on FTO substrate

The diffracted peaks of all the films are found to be along (111), (200), (220), (400) and (313) planes corresponding to

26.465, 31.175, 44.125, 65.479 and 70.741 2 $\theta$  values matching cubic phase of  $Cu_{1.8}S$  (ICDD file No. 01-075-2241).



Figure 2. The SEM images of stacked Cu1.8S nano plate lets (a) CE55 (b) CE60 (C) CE65 dep osite d o n FT O s ubstrates.

In the case of  $Cu_{2-x}S$ , identifying and attributing the corre phase is difficult since there exists many phases for the bulk  $Cu<sub>2-x</sub>S$  with its composition close to the ratio of Cu/S =2; like anilite, chalcocite, digenite, djurleite, which all have the maximum intensity diffraction peak at 46 degree of 2 $\theta$  value. However, in our case it is easy to identify the phase since; the diffraction plane at 44.5 degree occurs only for cubic phase of  $Cu<sub>1.8</sub>S$  and hence referred here after instead of  $Cu<sub>2-x</sub>S$ . The grain sizes were calculated from Scherer's method and are 112, 167 and 152 respectively for CE 55, CE60 and CE 63. The slight decrease in grain size for CE65 might be due to the reduced thickness of the nano platlets. The intensity of the diffraction plane <111> increases with increase in deposition temperature while <400> plane appears for CE 60. Even though, there is not much remarkable changes in the phase the Cu<sub>2-x</sub>S thin films, little changes in orientation of the nano platlets might have caused the disappearance of <400>plane for CE65 and is evidenced from the SEM images.

#### **3.2 Surface morphological studies and growth mechanism**

Figure 2 (a), (b) and (c) show the SEM images of the Cu<sub>1.8</sub>S thin films deposited at 55 °C (CE55), 60 °C (CE60) and 65 °C (CE65). respectively while Figure 2 (d), (e) and (f) display the cross section of the respective films. The surface of the CE55 exhibits uniform arrangement of stacked nano platelets with less density while raising the deposition temperature to 60 °C gives evenly distributed Cu<sub>1.8</sub>S of dense nano platelet with increased surface area to volume ratio. However, the surface morphology of the film deposited at 65 °C shows nar platelets with reduced thickness. The uniform surface morphology and high crystallinity of the  $Cu_{1.8}S$  is greatly influenced by CTAB, which allows the system to bypass se'  $agglomeration$  and provides capping and surface transformation to the Cu<sub>1.8</sub>S nanoplatelets. CTAB is basically strong cationic surfactant which can form micelles in the solution. Based on the solution conditions, CTAB form **RSCRIPT ADVANCES ADVANCES Advances Advances and Advances and Accepted Manuscripture**<br> **RSCCRIPT ADVANCES ADVANCES**<br>
TO THE MANUSCRIPT ADVANCES ADVANCES AND RESERVE TO THE MANUSCRIPT ADVANCES AND RESERVE TO THE MANUSCR

#### **ARTICLE Journal Name**

micelles of different shapes like cylindrical, spherical, high order lamellar to give crystals of different shapes<sup>27</sup>. The  $S^2$ ions generated through the hydrolysis of thioacetamide are readily attracted by  $Cu^{2+}$  ions and form a crab like Cu-S coordination bond  $^{26}$ . The supply of  $S^2$  ion is enhanced by acetic acid which also acts as a stabilizing agent. When cationic CTAB is introduced, it forms a micelle and is attract ed by S atoms present in the Cu<sub>1.8</sub>S. Apart from the prevention of self agglomeration by CTAB,  $\pi$ - $\pi$  bond interactions and weak Van der Waals attraction directs the reaction towards the formation of stable Cu $_{1.8}$ S nano platelets (Figure 3) $^{28, 29}$ . The preferential bonding between  $Cu^{2+}$  and  $S^{2-}$  leads to the selective formation of  $Cu<sub>1.8</sub>S$ . Due to the three dimensional surface of the thin films, the thickness of the films vary from place to place as revealed in the cross section of the film as seen in Figure 2 (d), (e) and (f).



Figure 3. The schematic of CTA B assisted Cu1.8S stacked na noplatelets formation on FTO s ubstrates.

#### **3.3 Optical Studies**



Figure 4. UV abs orption spectra of stacked  $Cu_{1.8}S$  nan oplate lets deposited on FTO substra tes.

Figure 4 compares the absorption spectra of the Cu<sub>1.8</sub>S thin films fabricated via CBD. All the films show absorption at

UV/visible region and is red shifted as the deposition temperature is increased due to quantum confined excitor effect and the absorption in NIR regions corres ponds to localized surface plasmon resonance (LSPR) due to free carrier density.

This is due to the presences of free holes (Cu vacancy) in the valance band that can act as self-dopants leadin to resonance absorption<sup>23</sup>. The absorption maximum in the UV/VIS is at 410, 417 and 475 nm respectively for CE55, CE60, CE65 samples with increased absorption. These high energy absorption peaks arises from the 1Sh - 1Se Figure 3. The schematic of CTAB assisted Cu1.8S stacked nanoplatelets formation on FTO substra tes.excitonic transition found in semiconductor nanoparticles<sup>30</sup>. From the absorption spectrum, the band gaps of the Cu<sub>1.8</sub>S thin films were calculated to  $\Box$ 2.2, 2.1 and 1.75 eV respectively for CE55, CD60, CE65. The reduction in the band gap is due to the formation of uniform crystals of increased size showing quantum confinement effect. On the longer wavelength region, non-stoichiometric  $Cu<sub>1.8</sub>S (x > 0)$  develops an LSPR in the NIR region and shifts to blue region with strong absorption due to higher free carrier come from increased copper vacancies.<sup>32</sup> The LSPR properties are always influenced by the surrounding medium and increase of the refractive index red shifts the NIR absorption of NCs. Here, the Cu<sub>1.8</sub>S films synthesized exhibit significant LSPR features with only air as the surrounding medium and hence the blue shift might come from the Cu deficiency  $2^{3,33,34}$ . The absorption of light in the NIR spectral window is also suitable to harvest the residual light penetrated from the tandem layered photoanode. This p-type semiconductor material can also contribute to the increase of the photo voltage with  $i$ . photoactive nature through the auxiliary tandem junction $^{1}$ . **RSCRIPT CONSTRUCTED**<br> **RSCRIPT CONSTRUCTED**<br> **RSCRIPT CONSTRUCTED**<br> **RSCRIPT** CONSTRUCTED OF PROPERTY OF PROPERTY OF PROPERTY



Figure 5. XPS survey spectra of Cu<sub>1.8</sub>S stacked nan oplatelets deposited on substra tes.

**3.4 XPS- Analysis**

#### **Journal Name ARTICLE**

The XPS analysis was utilized to infer the ionization states, elemental composition and to ensure the purity of the  $Cu<sub>1.8</sub>S$ thin films compounds. The samples were not subjected to any pre or post heat treatment. The presence of Cu, S, C and O elements are confirmed from the XPS survey spectrum presented in Figure 5**.** From the Auger line of Cu LMM at the binding energy of 569.0 eV, the presence of bivalent Cu is evidenced. The atomic % of Cu:S:O were 54.62:34.86:10.52, 62.18.36.3:1.45, 60.18:35.96:3.86 respectively for CE55, CE60 and CE65. CE55 shows very low S content due to slow sulfidation rate at low temperature and has more oxygen. On the other hand, both CE60 and CD65 have almost equal atomic % of S. In order to elucidate the nature of bonding of the surface elements, the individual core level spectra of S2p and  $Cu<sub>20</sub>$  were measured at higher rate of resolution. XPS data were fitted with Gaussian-Lorentzian (30 % Gaussian) functions and Shirley type background using Casa XPS Software. Four constraints were applied to fit S peak components such as the spin orbit splitting (1.18 eV between  $2P_{3/2}$  and  $2P_{\frac{1}{2}}$ ), the peak area ratio  $(2P_{3/2}: 2P_{1/2} = 2:1)$ , equal full width at half maximum and the binding energy positon of S  $2P_{3/2}$  was fixed at 161.2 eV. Figure 6 represents the individual  $S_{2p}$  peaks with clear distinction of their bonding whereas Cu does not show remarkable changes in the oxidation state and all spectra have satellite peaks due to Cu vacancy which have caused the LSPR in the optical spectra.<sup>23</sup>



Figure 6. XPS spectra for S2p of Cu<sub>1.8</sub>S nan oplate lets.

The S<sub>2p</sub> (S<sup>2</sup>) doublet peaks (161.2 and 162.38 eV) of Cu<sub>1.8</sub>S is attributed to the presence of  $S_{2p3/2}$  and  $S_{2p1/2}$  states. CE55 has both sulfide  $(SO_3^2)$  and sulfates  $(SO_4^2)$  respectively at 165.5 and 168 eV at the surface and are absent in CE60 and CE65. This clearly shows that oxidation is much higher for low S content samples prepared at low temperature. The peak found at 163.3 is assigned to bridging sulfur (S-S) which is at

lower binding energy state (less oxidation) in CE60, however, has Cu-S, disulfide  $(S_2^{2^2})$  and sulfide  $(S^2)$  peaks at 163.7, 16<sup>2</sup> and 161.2, respectively.  $35,36$ . The presence of S in the form of  $SO_4^2$  at surface of the films is in a residual form which is further confirmed from O1s peak located at 532.2eV in the survey spectrum<sup>37</sup>. These clearly show that the surface bonding is controlled by the temperature.



**Figure 7.** (a) I-V behavior for TiO<sub>2</sub>/CdS/CdSe/ZnS ODSSCs based on stacked Cu<sub>1 8</sub> nanopla telets and Pt counter electrodes. (b) Nyquist plot for Cu<sub>18</sub>S and Pt symmetrical cells: Inset shows equivalent circuit. (c) Tafel polarization plot for  $Cu<sub>1.8</sub>S$  and Pt symmetrical cells. (d) Nyquist plot of TiO  $_2$ /CdS/CdSe/ZnS QDSSCs for  $Cu_{1.8}$ S and Pt counter ele ctrodes . Inset shows the e quivalent circuit.

#### **3.5 IV Characteristics and Electrochemical Characterizations**

Figure 7 (a) shows the J-V characteristics of the QDSSCs fabricated with  $TiO<sub>2</sub>/CdS/CdSe/ZnS$  as the photoanode and CBD synthesized Cu<sub>1.8</sub>S and Pt (reference) as CE and polysulfide as electrolyte. The photovoltaic parameters are summarized in Table 1. The best photo conversion behavior is observed for CE60 with Voc = 0.606 V, JSC = 19.079 mA/cm<sup>-2</sup>, FF = 45.05 and  $η = 5.16 %$  and Pt CE shows Voc = 0.559 V,JSC = 6.671 mA/cm<sup>-2</sup> , FF = 31.71 and  $\eta$  = 1.45%. The affinity of Pt CE towards  $S^2$ accounts for its poor performance, which slows down the electrocatalytic activity of Pt with a rapid decrease in the current density and fails to reduce the redox electrolyte on it surface.<sup>38,39</sup> All the Cu<sub>1.8</sub>S CEs give better performance than Pt and among the Cu<sub>1.8</sub>S CEs, the performance of CE60 is better than the rest. The surface active S species are very crucial for the electrolyte reduction. However, bridging S-S is more resistive than Cu-S bond presence in CE 60. Hence, the improvement might have come from the surface active specis in addition to the surface morphology influenced by CTAb which plays a role of structure directing agent to improve  $t$   $\ge$ shape and surface morphology and in turn the photol conversion ability. The stacked platelets like structu **RSCRIPT ADVANCES ADVANCES ADVANCES Advances the contract of the second of the contract of the second of** 

#### **ARTICLE Journal Name**

possesses increased surface to volume ratio that provides larger area of contact for the electrolyte. The interfaces between the stacked layers too offer space for the electrolyte to flow. Therefore the redox reaction of the electrolyte is enhanced. Even though, efficiency is much higher than the earlier reports,  $2^{3,26}$  the FF is much lower which might be due to higher charge transfer resistance  $(R<sub>CT</sub>)$  of the QDSSC.

The scavenging attitude of the sulfide ions  $(S^2)$  over the photogenerated holes at the photo anode and the oxidized ions  $(S_x^2)$  to reach the CE in order to combine with the electron, must be enhanced by the CE. $^{\rm 1}$ 

Therefore, the charge transfer resistance  $(R<sub>CT</sub>)$  of the QDSSC, which determines the electrocatalytic activity of the counter electrode has to be studied by using electrochemical impedance spectroscopy (EIS). Figure 7(b) shows the Nyquist plots of the symmetrical cells and the equivalent circuit (inset) is made with a series resistance (Rs) which represents a highfrequency non zero intercepts on the real axis, the resistance at the counter electrode electrolyte interface  $(R_{CF})$  and the respective capacitance  $(C_{PF})$  with the diffusion impedance  $(Z_W)$ represented by a saturated semicircle usually observed at the low frequency. The symmetrical cells were made of two identical Cu<sub>1.8</sub>S and Pt CEs respectively with an active area of 1 cm 2 and the polysulfide electrode in between them. The measurements were carried out in the frequency range of 0.1 Hz - 500 kHz. The obtained impedance data were fitted using the equivalent circuit given in the inset and the parameters extracted are presented in table1. The value of  $R_s$  for the Cu $_{1.8}$ S CEs decreases as the deposition temperature is increased indicating better adhesion of the  $Cu<sub>1.8</sub>S$  thin films on to the FTO substrate. The extent of  $R_{CF}$  determines the charge transfer between the CE and the electrolyte towards the redox reaction of  $S^{2-}/S_n^{2-}$ . It is found that Pt CE has highest R<sub>CE</sub> value of 576.23 Ω against the very small values for Cu<sub>1.8</sub>S CEs, and among Cu<sub>1.8</sub>S CEs, CE60 has the lowest value of 3.26 Ω while CE55 and CE65 have larger  $R_{CE}$  values than CE 60 and therefore this accounts for the enhanced performance of CE60. The diffusion impedance  $(Z_w)$  is yet another yardstick to determine the ability of a CE in reducing the redox polysulfide electrolyte. Pt CE has the highest value of 102.58 Ω suggesting poor ability

and strong resistance to reduce the electrolyte as catalytic poisoning hinters.  $40,41$  On the contrary, the Cu<sub>1.8</sub>S CE with very negligible values outperform Pt CE (CE55 = 1.49 Ω, CE60 = 0.34  $Ω$  and CE 65 = 0.76  $Ω$  (Not shown in the table).

In order throw light on the better electrocatalytic activity and the interfacial charge transfer property of  $S^{2-}/S_n^{2-}$  redox couple Tafel polarization measurement was carried out using the symmetrical cells. Figure 7 (c) shows the logarithmic current density (log J) as a function of Voltage (V) for the redox reaction of polysulfide electrolyte redox couple  $(S^2 / S_n^2)$ . By extrapolating the linear region of the curve towards the zero over potential and from the intercept, the exchange current density  $(J_0)$  was obtained. The exchange current density  $(J_0)$ and limiting current density (J<sub>lim</sub>) determine electrochemical activity of the CE. As seen in Figure 7 (c), except Pt all the CEs show almost even anodic and cathodic slopes. CE60 shows higher slope both on anodic and cathodic side with  $ze^{-}$ corrosion potential. Its highest limiting current density  $(J_{\text{lim}})$ , highest corrosion current of  $3245.61$   $\mu$ A and balanced oxidation and reduction rate is confirmed from its equal cathodic (βc) (298.0 mV) and anodic slopes (βa) (300.1 mV) further support its best performance, yielding an efficiency of 5.16%. CE55 and CE65 stay behind CE60 with lower corrosic current ( $I_{corr}$ ) of 2778.95  $\mu$ A and 2285.68  $\mu$ A respectively. CE 65 has slightly predominant cathodic slope (βc) (299.7mV) over that of anodic slope (βa) (286.4mV) with corrosion potential of  $(E_{corr})$  -1.843mV and therefore a slight shift from the equilibrium reduces their catalytic activity. CE 55 with lowest limiting current density  $(\mathsf{J}_{\mathsf{lim}})$  and high corrosion potential ( $E_{corr}$ ) of -7.512mV becomes the least performing counter electrode. In addition to that uneven cathodic and anodic slopes also ( $\beta$ c = 283.4mV,  $\beta$ a = 310.6 mV) make inferior among the  $Cu_{1.8}S$  counter electrodes. In the case of Pt CE, it not only has uneven cathodic and anodic slopes, ( $βc =$ 290.00mV, βa = 330.2mV) and lowest limiting current density  $(J_{\text{lim}})$ , but also has negative corrosion potential (E<sub>corr</sub>) of -18.16 mV. Pt CE'S large negative corrosion potential ( $E_{corr}$ ) means that when all the Cu<sub>1.8</sub>SCEs can readily reduce the polysulfide electrolyte Pt CE has to attain equilibrium (null point) prior to its commencement of reduction of polysulfide electrolyte at **RSCREED ACCEPTS**<br> **RSCREED ACCEPTS** 



**6** | *J. Nam e*., 2012, **0 0**, 1 -3 This journal is © The Royal Society of Chemistry 20xx

#### **Journal Name ARTICLE**

the expense of photoconversion ability.<sup>20</sup>To support the above said reasons for the better electrocatalytic activity of CE60, the internal charge transfer kinetics must be explained from EIS point of view. The EIS measurements for the QDSSCs were carried out at open circuit voltage ( $V_{\text{oc}}$ ) (light condition). The impedance data were fitted using the equivalent circuit given in the inset in Figure 7 (d). In the circuit  $R_{CE}$  represents electron transfer at the counter electrode/polysulfide electrolyte interface,  $R_{CT}$  represents charge transfer resistance at the photoanode/polysulfide electrolyte interface and  $C_{PE}$  is the chemical capacitance related to amount of photoexcited charge carriers available in the conduction band of the photoanode which result from minimum recombination and  $Z_w$  is the diffusion resistance. The QDSSC assembled with CE60 gives an R<sub>CE</sub> of 1.7  $\Omega$  and Z<sub>W</sub> = 1.17  $\Omega$  showing better reduction rate of the electrolyte and electrolyte diffusion. On the contrary Pt CE with a high R<sub>CE</sub> = 12.32  $\Omega$  and Z<sub>W</sub> = 10.24  $\Omega$  as it is subjected to adsorption of  $S<sup>2</sup>$  makes it poor to reduce the electrolyte with the supply of electron. Therefore, Pt CE fails to have better photoconversion ability and reduced FF, while all the Cu<sub>1.8</sub>S CEs have high J<sub>SC</sub> and photo conversion ability. The best photoconversion efficiency demonstrated by CE60 is due to i) have low resistance and ii) have zero corrosion potential implies that the system is already at equilibrium to readily reduce the electrolyte unlike Pt whose negative corrosion potential must be balanced with additional sacrifice of energy. <sup>42</sup>



Figure 8: Comparison of I-V parameters variation with aging time for the QDSSC assembled with CE60: (a) open circuit voltage (b) fill factor (c) short current density (d) efficiency

For the best performing QDSSc, stability test was conducted by exposing the cell for 20 continuous hours under light illumination and presented in figure 8. It is found that the cell showed consistent photoconversion efficiency with minimum decrement of only 2.1% in the efficiency. The photoconversi on efficiency was found to increase after sufficient exposure to the light illumination since the heating of the electrolyte

improves the ionic mobility with good penetration of the electrolyte in to the pores of TiO<sub>2</sub> because of capillary effect.<sup>43,44</sup> Therfore Cu<sub>1.8</sub>S can be a suitable cost-effective substitute to Pt as counter electrode material with superior electrocatalytic property, high stability and commendable longevity.

# **4. Conclusion**

Stacked nanoplatelets of  $Cu<sub>1.8</sub>S$  were synthesized using CTAE as surfactant. CTAB is found to influence the surface morphology of the Cu<sub>1.8</sub>S thin films and yields highly crystalline Cu<sub>1.8</sub>S. The electrocatalytic behavior of the Cu<sub>1.8</sub>S CEs is greatly influenced by the surface morphology and surface active sulfide species. All the QDSSCs assembled  $Cu<sub>1.8</sub>$ S CEs exhibit over 3.87 % of photoconversion efficiency and highe. photoconversion efficiency of 5.16% is achieved for the film synthesized at 60  $^{\circ}$ C with very low R<sub>S</sub>, R<sub>CT</sub>, R<sub>CE</sub> and Z<sub>W</sub> values and zero corrosion potential against the poor electrocatalytic behavior of Pt owing to catalytic poisoning. The free carrier concentration due to Cu vacancy and the Cu-S bonding at the surface of the counter electrode found to play key role in redox reaction. The electrocatalytic feature of  $Cu<sub>1.8</sub>S$  makes it suitable cost-effective alternate to Pt as counter electrode. **RSC Advances Accepted Manuscript**

## **Author Inform ation**

## **Corresponding Author**

\*prabakar@pusan.ac.kr, \*kprabakar@gmail.com

## **Conflict of Interest**

The authors declare no competing financial interests.

#### **Acknowledgements**

This work was supported for two years by the Pusan National University research grant.

#### **References**

- 1. C. Lin, C. Teng, T. Li, Y. Lee and H. Teng, *J. Mater. Chem. A,* 2013, **1**, 1155-1162.
- 2. I. Mora-Sero, S. Gimaenez, F. Fabregat-Santiago, R. Gomez, Q. Shen, T. Toyoda and J. Bisquert, *Acc. Chem. Res.,* 2009, **42**, 1848-1857.
- 3. S. Buhbut, S. Itzhakov, E. Tauber, M. Shalom, I. Hod, T. Geiger, Y. Garini, D. Oron and A. Zaban, *ACS Nano,*  2010, **4**, 1293-1298.
- 4. L. M. Peter, K. G. U. Wijayantha, D. J. Riley and J. Waggett, *J Phys Chem B,* 2003, **107**, 8378-8381 .
- 5. M. Shalom, I. Hod, Z. Tachan, S. Buhbut, S. Tirosh and A. Zaban, *Energy Environ. Sci.,* 2011, **4**, 1874-1878 .
- 6. W. W. Yu, L. Qu, W. Guo and X. Peng, *Chem. Mater.,*  2003, **15**, 2854-2860.

**ARTICLE Journal Name**

- 7. P. Wang, S. M. Zakeeruddin, J. E. Moser, R. Humphry-Baker, P. Comte, V. Aranyos, A. Hagfeldt, M. K. Nazeeruddin and M. Grätzel, *Adv Mater,* 2004, **16**, 1806-1811.
- 8. R. Vogel, K. Pohl and H. Weller, *Chemical Physics Letters,* 1990, **174**, 241-246.
- 9. R. Vogel, P. Hoyer and H. Weller, *J. Phys. Chem.,* 1994, **98**, 3183-3188.
- 10. H. Wang, T. Kubo, J. Nakazaki, T. Kinoshita and H. Segawa, *J. Phys. Chem. Lett.,* 2013, **4**, 2455-2460.
- 11. L. Li, X. Yang, J. Gao, H. Tian, J. Zhao, A. Hagfeldt and L. Sun, *J. Am. Chem. Soc.,* 2011, **133**, 8458-8460.
- 12. J. Tian, R. Gao, Q. Zhang, S. Zhang, Y. Li, J. Lan, X. Qu and G. Cao, *J. Phys. Chem. C,* 2012, **116**, 18655-18662.
- 13. M. Kim, A. Ochirbat and H. J. Lee, *Langmuir,* 2015, **31,** 7609–7615.
- 14. K. Imoto, K. Takahashi, T. Yamaguchi, T. Komura, J. Nakamura and K. Murata, *Solar Energy Mater. Solar Cells,* 2003, **79**, 459-469.
- 15. G. Hodes, J. Manassen and D. Cahen, *J. Electrochem. Soc.,* 1980, **127**, 544-549.
- 16. Y. Lee and Y. Lo, *Advanced Functional Materials, 2*009, **19,** 604-609.
- 17. A. Banerjee, K. K. Upadhyay, S. Bhatnagar, M. Tathavadekar, U. Bansode, S. Agarkar and S. B. Ogale, *RSC Adv.,* 2014, **4**, 8289-8294.
- 18. W. J. Lee, E. Ramasamy, D. Y. Lee and J. S. Song, *ACS Appl. Mater. Interfaces,* 2009, **1**, 1145-1149.
- 19. M. Gao, Y. Xu, J. Jiang and S. Yu, *Chem. Soc. Rev.,*  2013, **42**, 2986-3017.
- 20. X. Rui, H. Tan and Q. Yan, *Nanoscale,* 2014, **6**, 9889- 9924.
- 21. Y. Hou, D. Wang, X. H. Yang, W. Q. Fang, B. Zhang, H. F. Wang, G. Z. Lu, P. Hu, H. J. Zhao and H. G. Yang, *Nat Commun,* 2013, **4**, 1583.
- 22. L. Zhang, H. K. Mulmudi, S. K. Batabyal, Y. M. Lam and S. G. Mhaisalkar, *Phys. Chem. Chem. Phys.,* 2012, **14**, 9906-9911.
- 23. A. Dennyson Savariraj, K. K. Viswanathan and K. Prabakar, Electrochimica Acta 2014, **149**, 364-369.
- 24. H. Wu and W. Chen, *Nanoscale,* 2011, **3**, 5096-5102.
- 25. C. Burda, X. Chen, R. Na rayanan and M. El-Sayed, *Chem. Rev.,* 2005, **105**, 1025-1102.
- 26. A. Dennyson Savariraj, K. K. Viswanathan and K. Prabakar, *ACS Appl. Mater. Interfaces,* 2014, **6** , 19702–19709.
- 27. C. Wu, G. Zhou, D. Mao, Z. Zhang, Y. Wu, W. Wang, L. Luo, L. Wang, Y. Yu, J. Hu, Z. Zhu, Y. Zhang and J. Jie, *Journal of Materials Science & Technology,* 2013, **29**, 1047-1052.
- 28. M. Saranya, C. Santhosh, R. Ramachandran, P. Kollu, P. Saravanan, M. Vinoba, S. K. Jeong and A. N. Grace, *Powder Technol, 2*014, **252,** 25-32.
- 29. Q. Lu, F. Gao and D. Zhao, *Nano Lett.,* 2002, **2**, 725- 728.
- 30. J. M. Luther, P. K. Jain, T. Ewers and A. P. Alivisatos, *Nat Mater,* 2011, **10**, 361-366.
- 31. I. Kriegel, C. Jiang, J. Rodri guez-Fernandez, R. D. Schaller, D. V. Talapin, E. da Como and J. Feldmann, *J. Am. Chem. Soc.,* 2012, **134**, 1583-1590.
- 32. D. Dorfs, T. Hartling, K. Miszta, N. C. Bigall, M. R. Kim, A. Genovese, A. Falqui, M. Povia and L. Manna, *J. Am. Chem. Soc.,* 2011, **133**, 11175-11180.
- 33. D. Dorfs, T. Hartling, K. Miszta, N. C. Bigall, M. R. Kim, A. Genovese, A. Falqui, M. Povia and L. Manna, *J. Am. Chem. Soc.,* 2011, **133**, 11175-11180.
- 34. Y. Liu and C. Z. Huang, *Nanoscale,* 2013, **5**, 7458- 7466.
- 35. R.St.C. Smart, W.M. Skinner and A.R. Gerson, *Suf. Interface Anal.* 1999, **28**, 101-105.
- 36. K. Laajalehto, I. Kartio and P. Nowak, Appl. Surf. Sci 1994, **81**, 11-15.
- 37. Y. Lu, X. Meng, G. Yi and J. Jia, *J. Colloid Interface Sci., 2*011, **356,** 726-733.
- 38. Z. Yang, C. Chen, C. Liu and H. Chang, Chen *Commun.,* 2010, **46**, 5485-5487.
- 39. J. G. Radich, R. Dwyer and P. V. Kamat, *J. Phys. Chem. Lett., 2*011, **2,** 2453-2460.
- 40. V. A. Sethuraman and J. W. Weidner, *Electrochim. Acta,* 2010, **55**, 5683-5694.
- 41. F. Xie, Z. Shao, G. Zhang, J. Zhai, W. Lu, X. Qin, W. Li and B. Yi, *Electrochim. Acta,* 2012, **67**, 50-54.
- 42. X. Feng, K. Shankar, M. Paulose and C. A. Grimes, *Angewandte Chemie International Edition,* 2009, **48**, 8095-8098.
- 43. K. Zhao, H. Yu, H. Zhang and X. Zhong, *J. Phys. Chem. C, 2*014, **118,** 5683-5690.
- 44. H. McDaniel, N. Fuke, N. S. Makarov, J. M. Pietryga and V. I. Klimov, *Nat Commun,* 2013, **4** :2887.

**RSC Advances Accepted Manuscript SC Advance** 

**8** | *J. Nam e*., 2012, **0 0**, 1 -3 This journal is © The Royal Society of Chemistry 20xx

# **Table of Contents**

